	Document Title: IC Material Content	Document Number: PD00007
	Description: Statement of material Content	Doc: Process Doc
	Confidential	Page.....................Of.....................

STATEMENT of MATERIAL CONTENT

Part Number(s)
Date:

Detail	Unit	Package
PACKAGE MATERIALS		
FT Package ID		
Pin/Lead Count		
FT package P/N		
Package Manufacturer		
Mfg Pkg ID/FT part ID/Dwg ID		
FT package Outline		
JEDEC Case Outline		
Mil Case Outline ID		
Assembly Facility		
Plant		
Leadframe Plating		
Plating Process		
Ceramic		
Lead Braze		
Leads		
Lead Plating [Gold Finish]		
Cropping		
Leads [Hot Solder Dip Finish]		
PACKAGE DIMENSIONS & CHARACTERISTICS		
Nominal Cavity Volume		
Die Size		
Pad Size		
Theta Ja [still air] -approx		
Theta Ja [200fpm/1mps] - approx		
Theta Jc		
Lead Resistance		
Lead to Lead Capacitance		
SHIPPING INFORMATION		
Carrier Type		
Units Per Rail		
Total Product Weight		
LID DETAIL		
Manufacturer		
Lid Type		
FT Lid ID		
Dimensions		
Lid Material		
Plating		
Plating Process		
Frame		
Frame Thickness		
ASSEMBLY MATERIALS		
Die Attach		
Manufacturer		
Die Attach Type		
Die Attach Thickness		
Die Thickness		
Die Coating		
Wire Bond Material		
Wire Bond Diameter		

Notes:

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